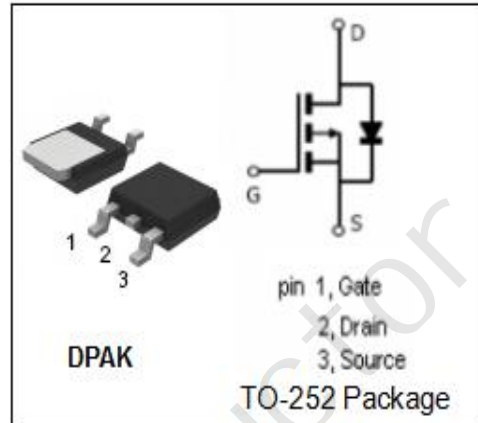


• FEATURES

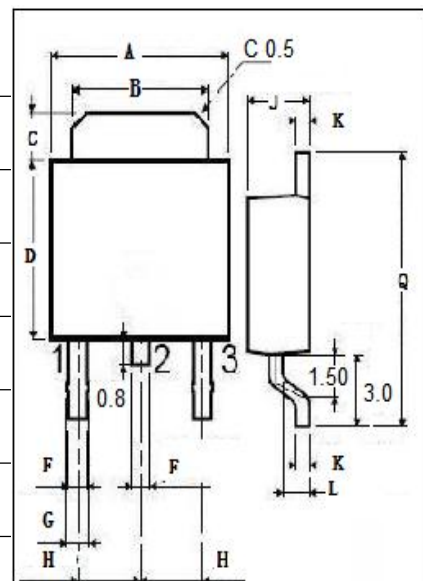
- TO-252(DPAK) packaging
- High speed switching
- Low gate input resistance
- Standard level gate drive
- Easy to use
- 100% avalanche tested
- Minimum Lot-to-Lot variations for robust device performance and reliable operation


• APPLICATIONS

- Power supply
- Switching applications

• ABSOLUTE MAXIMUM RATINGS(T_a=25°C)

SYMBOL	PARAMETER	VALUE	UNIT
V _{DSS}	Drain-Source Voltage	-60	V
V _{GSS}	Gate-Source Voltage	±20	V
I _D	Drain Current-Continuous@T _c =25°C T _c =100°C	-26 -18	A
I _{DM}	Drain Current-Single Pulsed	-60	A
P _D	Total Dissipation	60	W
T _j	Operating Junction Temperature	175	°C
T _{stg}	Storage Temperature	-55~175	°C



DIM	mm	
	MIN	MAX
A	6.40	6.60
B	5.20	5.40
C	1.15	1.35
D	5.70	6.10
F	0.65	
G	0.75	
H	2.10	2.50
J	2.10	2.40
K	0.40	0.60
L	0.90	1.10
Q	9.90	10.1

• THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	MAX	UNIT
R _{th(ch-c)}	Channel-to-case thermal resistance	2.5	°C/W
R _{th(ch-a)}	Channel-to-ambient thermal resistance	50	°C/W

ELECTRICAL CHARACTERISTICS

 T_c=25°C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V; I _D = -0.25mA	-60			V
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} ; I _D =-0.25mA	-1.2		-2.4	V
R _{DS(on)}	Drain-Source On-Resistance	V _{GS} = -10V; I _D =-20A		32	40	mΩ
I _{GSS}	Gate-Source Leakage Current	V _{GS} = ±20V; V _{DS} = 0V			±0.1	μA
I _{DSS}	Drain-Source Leakage Current	V _{DS} = -48V; V _{GS} = 0V; T _j =25°C T _j =55°C			-1 -5	μA
V _{SDF}	Diode forward voltage	I _{SD} =-1A, V _{GS} = 0 V			-1	V